Technical Program at a Glance

Time	Tuesday • April 9		Wednesday • April 10		Thursday•April 11	
8:00 AM	Opening & Keynote		Parallel Session 3A	Parallel Session 3C	Plenary Session 5 on	
8:25 AM			ESD & Latchup	Failure Analysis	Process Induced	
8:50 AM	Plenary Session 1 on		+ 4 papers	four papers	Damage	
9:15 AM	Non-Volatile Memories				1 invited review	
9:40 AM	Six platform presentations		extra time to check out the exhibits		+ 4 papers	
10:05 AM Break						
10:30 AM			зв Compound	3D Product	Panel Discussion	
10:55 AM			Semiconductors I	Reliability I	Product	
11:20 AM			3 papers	3 papers	Qualification	
11:45 AM	Dielectrics:ESREF Best Paper					
12:10 PM						
12:35 PM						
1:00 PM						
1:25 PM						
1:35 PM					SPECIAL TOPIC	
2:00 PM	Parallel Session 2A	Parallel Session 2C	4A Compound	4c Product	Irradation (Germicidal)	
2:25 PM	Dielectrics I	MEMS	Semiconductors II	Reliability II	3 papers	
2:50 PM	four platform	2 invited reviews	3 papers	3 papers	Plenary Session 6 on	
3:15 PM	presentations	+ 2 papers	4C Device &	4D Interconnects	Dielectrics II	
3:40:00 PM Break						
4:05 PM	2B Hot Carriers	2D Assy/Pkg	Process	1 invited review	5 papers	
4:30 PM	five platform	3 invited reviews	5 papers	+ 5 papers'		
4:55 PM	presentations	+1 paper				
5:20 PM						
5:45 PM						
6:10 PM	-					
6:35 PM						
7:00 PM	Symposium Reception with					
	Jack Kilby		Workshops - 7:30 pm			
	&					
	15 poster presentations					
	Apirl 7, Sunday NIGHT additional SER Workshop - Panel Discussion					